

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

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Claim 1. (amended) A semiconductor device comprising:

- a. a leadframe including a plurality of leads ~~extending therefrom~~, a first source attach area on a first surface of the leadframe and a first gate attach area, and a second source attach area on a second surface of the leadframe and a second gate attach area;
- b. at least two dies, a first ~~of which is die being electrically coupled to the~~ first source and gate attach areas of the leadframe and a second ~~of which is die being electrically coupled to the second source and gate attach areas of the leadframe~~;
- c. a drain connection assembly coupled to a drain region of the first die; and,
- d. ~~a body, the body being coupled to the semiconductor device being around at least a portion of the first die and the second die, such that at least~~ a drain region of the second die is exposed by the body,

wherein the first and second dies are in a stacked relationship and are at opposite sides of the leadframe, and wherein the drain region of the first die faces away from the leadframe and the drain region of the second die faces away from the leadframe.

Claim 2. (original) A semiconductor device in accordance with claim 1 wherein at least one of the dies is a bumped die.

Claim 3. (original) A semiconductor device in accordance with claim 2 wherein both dies are bumped dies.

Claim 4. (currently amended) A semiconductor device in accordance with claim 1 wherein the drain connection assembly comprises a drain clip and a ~~lead~~ side rail adjacent an edge of the drain clip.

Appl. No. 09/805,597  
Amdt. dated August 1, 2003  
Reply to Office Action of February 4, 2003

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Claims 5.-6. (canceled)

Claim. 7. (new) A semiconductor device in accordance with claim 1 wherein the drain connection assembly comprises a drain clip and a side rail adjacent an edge of the drain clip, and wherein the side rail comprises a v-groove.

*B11*  
Claim 8. (New) A semiconductor device in accordance with claim 1 wherein the drain connection assembly comprises a drain clip and a side rail adjacent an edge of the drain clip, and wherein the side rail comprises a v-groove, and wherein the drain clip comprises copper.